Pending Claims

This listing of claims is a courtesy copy of the pending claims. No amendments have been made in this Reply.

- 1. (Previously Amended) A key pad assembly comprising:
 - a top cover placed over a stack of keypad components;
- a bottom cover placed under the stack; the top cover and the bottom cover defining a common perimeter; and

an over molded portion that extends around the perimeter to form a self contained key pad unit.

- 2. (Previously Presented) The key pad assembly of claim 1, the top cover and the bottom cover sandwich the stack.
- 3. (Original) The key pad assembly of claim 1, the top cover and the bottom cover are over molded to create a sealed common boundary.
- 4. (Original) The key pad assembly of claim 1, the stack comprises a printed circuit board with a flex member, an electro luminous panel, a silicone membrane with a plurality of keys, placed on top of each other.
- 5. (Original) The key pad assembly of claim 3, the flex member provides an electrical connection between the self contained key pad unit and a device that hosts the self contained key pad unit.
- 6. (Previously Cancelled).
- 7. (Original) The key pad assembly of claim 5, the flex member protrudes out a trough of the self contained key pad unit.

- 8. (Previously Presented) The key pad assembly of claim 1, the bottom cover with a recess that houses a speaker therein.
- 9. (Previously Presented) The key pad assembly of claim 1, the top cover and bottom cover fabricated from at least one of polycarbonates, thermoset plastics, or thermoformed plastic.
- 10. (Original) The key pad assembly of claim 1, an illumination color or a brightness on a surface of the keypad indicates a mode of the key pad.
- 11. (Previously amended) A method of fabricating a self contained key pad comprising:

sandwiching a plurality of key pad components between a top cover and a bottom cover, the top cover and bottom cover defining a common perimeter; and

inserting molding around the perimeter for encapsulating the top cover and the bottom cover.

- 12. (Original) The method of claim 11 further comprising sandwiching the key pad components between the top and bottom cover.
- 13. (Original) The method of claim 11 further comprising housing a speaker in a recess of the bottom cover.
- 14. (Original) The method of claim 11 further comprising providing electrical connections to a host unit *via* a flex member.
- 15. (Previously Cancelled).

- 16. (Previously amended) A self contained key pad comprising:
 - a stack comprising:
 - a membrane with a plurality of keys placed thereupon,
 - a printed circuit board positioned beneath the membrane;
 - a top cover placed over the stack; and
- a bottom cover placed under the stack, the top cover and the bottom cover define a common boundary around the stack, the common boundary over molded to encapsulate the stack between the bottom cover and the top cover.
- 17. (Original) The self contained key pad of claim 16, the common boundary includes a contact surface of the top and bottom cover.
- 18. (Original) The self contained key pad of claim 18, the common boundary includes a perimeter common to the top and bottom cover.
- 19. (Original) The self contained key pad of claim 18, the bottom cover connected to a piezo electric speaker.
- 20. (Original) The self contained key pad of claim 18, the bottom cover contacts the printed circuit board.
- 21. (Original) The self contained key pad of claim 18, the top cover and the bottom cover sandwich the stack.
- 22. (Previously Cancelled).
- 23. (Previously Presented) The key pad assembly of claim 1 further comprising an identification component that automatically identifies the key pad to a device that hosts the self contained key pad assembly.

24. (Previously Presented) The self contained key pad of claim 16 further comprising an identification component that automatically identifies the self contained key pad to a device that hosts the self contained key pad.